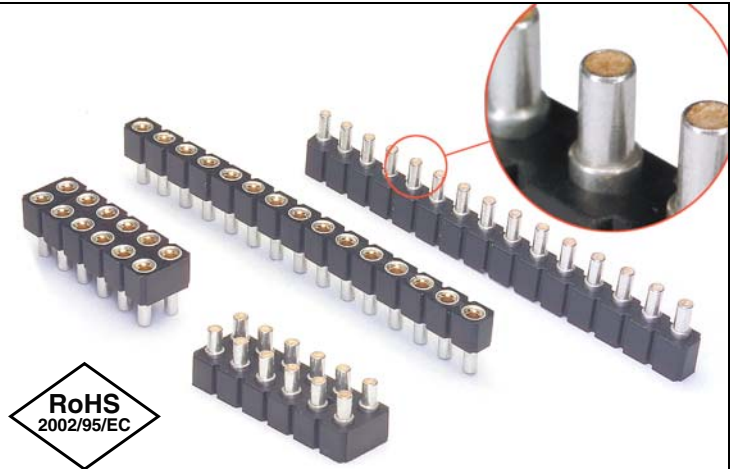
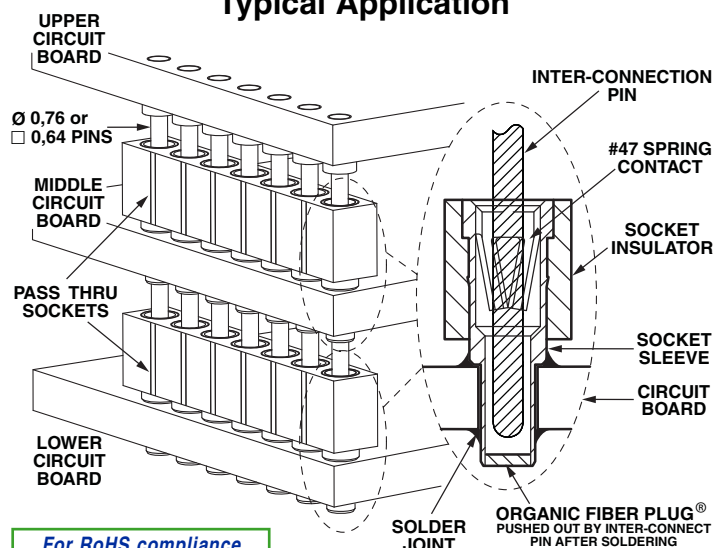


- 834/835 Series Pass Through Sockets have a low 3,30 profile and will accept Ø 0,76 round pin, as well as industry standard 0,64 square pin headers.
- They are typically used to interconnect two or more parallel circuit boards.
- Sockets are designed for hand, wave or reflow* soldering. The high temp. insulator is compatible with all solder processes.
- Unique **ORGANIC FIBRE PLUG®** barriers prevent solder, paste or flux from contaminating the internal spring contacts. After soldering, the **OFP®** barriers are pushed out of the socket when the mating header is inserted.
- Mill-Max sockets use a precision-machined brass sleeve with a press-fit beryllium copper "multi-finger" spring contact.
- Recommended mounting holes are Ø 1,17 ±0,08 PTH (1,2 mm drilled prior to plating).

**Intrusive reflow (also called "pin-in-paste") is a technique of using conventional through-hole components in a reflow soldering process. The pass through socket is placed into plated through-holes in the circuit board (solder paste has previously been screen printed on pads adjacent to the holes) and the board is reflowed in the same pass as other SMT components. Solder will fill the plated through-holes and achieve solder joints as reliable as wave soldering. The OFP® barrier prevents solder paste from being picked-up inside the contact during assembly.*



Typical Application



For RoHS compliance select ◇ plating code.

US Patent #7,086,870

Ordering Information

Fig. 1	Single Row OFP® Pass Through Socket	
	834-XX-0	-10-001000
	Specify # of pins	→ 01-64
Fig. 2	Double Row OFP® Pass Through Socket	
	835-XX-0	-10-001000
	Specify # of pins	→ 02-72

For Electrical, Mechanical & Environmental Data, See pg. 4

XX=Plating Code See Below

SPECIFY PLATING CODE XX=	93	43◇
Sleeve (Pin)	5,08µm Sn/Pb	5,08µm Sn
Contact (Clip)	0,76µm Au	0,76µm Au

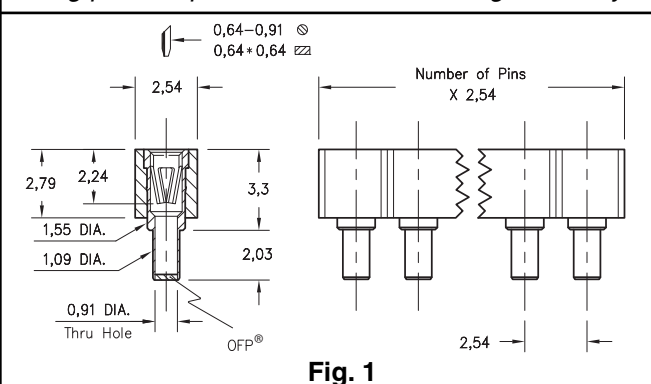


Fig. 1

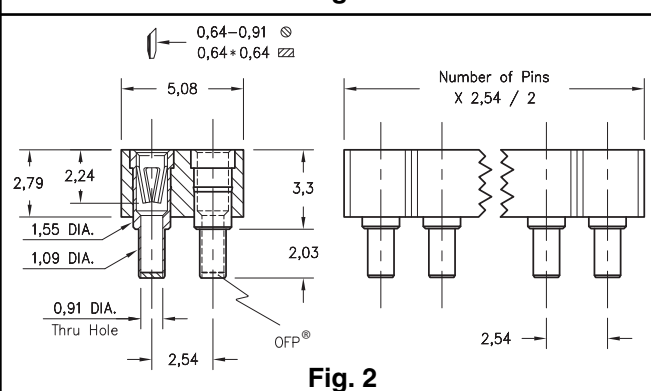


Fig. 2